

# CPA1H1J050F

17.3 – 18.4 GHz, 60 W GaN HPA

## Description

The CPA1H1J050F is a 60W package MMIC HPA utilizing the high performance, 0.15um GaN on SiC production process. The CPA1H1J050F operates from 17.3-18.4 GHz and supports Direct Broadcast Satellite communications. The CPA1H1J050F achieves 60 W of saturated output power with 25 dB of large signal gain and typically 30% power-added efficiency under CW operation.

Packaged in a 17.5 x 24 mm bolt-down, flange package, the CPA1H1J050F provides superior RF performance and thermal management allowing customers to improve SWaP-C benchmarks in their next-generation systems.



Figure 1. CPA1H1J050F

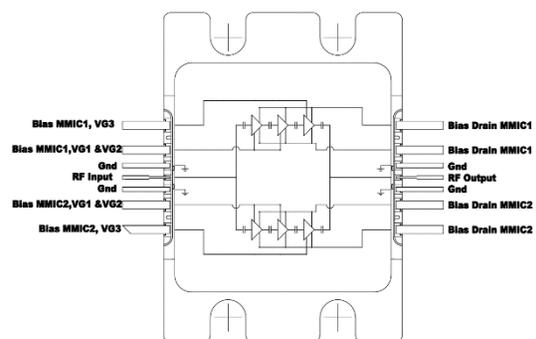


Figure 2. Functional Block Diagram

## Features

- Psat: 60 W
- PAE: 30 %
- LSG: 25 dB
- S21: 30 dB
- S11: -10 dB
- S22: -6 dB
- CW operation

## Applications

- Direct Broadcast Satcom

Note: Features are typical performance across frequency under 25°C operation. Please reference performance charts for additional information.



### Absolute Maximum Ratings

Parameter	Symbol	Units	Value	Conditions
Drain to Source Voltage	$V_{DSS}$	V	84	
Drain Voltage	$V_D$	V	28	
Gate Voltage	$V_G$	V	10, +2	
Drain Current	$I_D$	A	12.8	
Gate Current	$I_G$	mA	24.6	
Input Power	$P_{in}$	dBm	26	
Dissipated Power	$P_{diss}$	W	160	85°C
Storage Temperature	$T_{stg}$	°C	-55, +150	
Mounting Temperature	$T_J$	°C	320	30 seconds
Junction Temperature	$T_J$	°C	225	MTTF > 1E6
Output Mismatch Stress	VSWR	Ψ	3:1	

### Recommended Operating Conditions

Parameter	Symbol	Units	Typical Value	Conditions
Drain Voltage	Vd	V	28	
Gate Voltage	Vg	V	-1.9	
Drain Current	Idq	mA	700	
Input Power	Pin	dBm	23	CW
Case Temperature	Tcase	°C	-40 to 85	

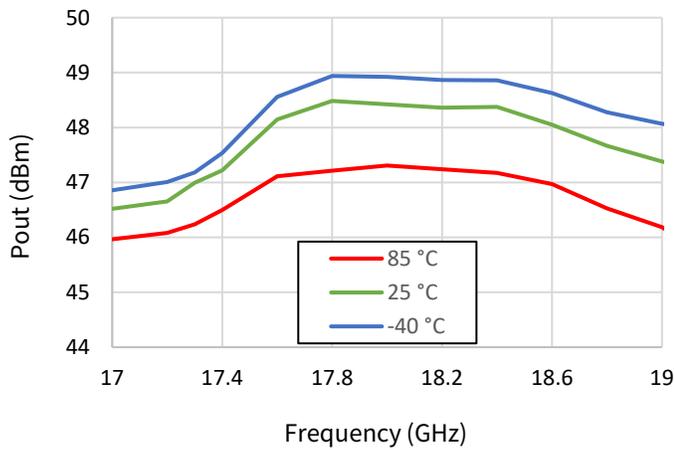
### RF Specifications

Test conditions unless otherwise noted: Vd=28 V, Idq=0.7A, CW, Pin = 23 dBm, T<sub>base</sub>=25°C

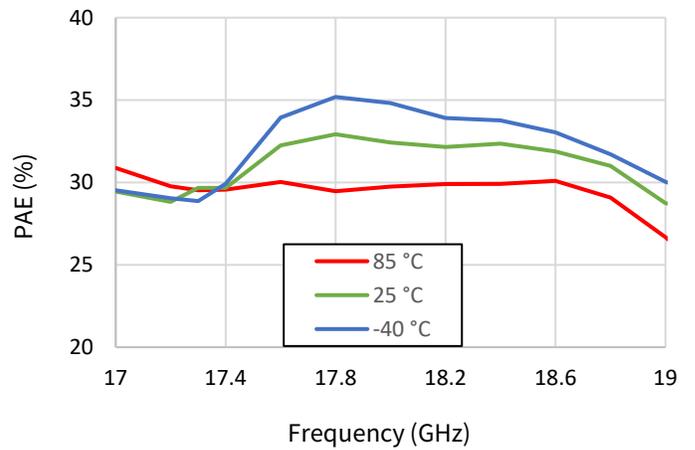
Parameter	Units	Frequency	Min	Typical	Max	Conditions
Frequency	GHz		17.3		18.4	
Output Power	dBm	17.3		47.0		
		17.8		48.5		
		18.4		48.0		
Power-added Efficiency	%	17.3		30		
		17.8		32		
		18.4		32		
LSG	dB	17.3		24.0		
		17.8		25.5		
		18.4		25.0		
Small-Signal Gain	dB	17.3		30		Pin = -20 dBm
		17.8		30		
		18.4		30		
Input Return Loss	dB			10		Pin = -20 dBm
Output Return Loss	dB			6		Pin = -20 dBm

Test conditions unless otherwise noted:  $V_d=28\text{ V}$ ,  $I_{dQ}=0.7\text{ A}$ , CW,  $P_{in} = 23\text{ dBm}$ ,  $T_{base}=25\text{ }^\circ\text{C}$ , Frequency: 17.8GHz

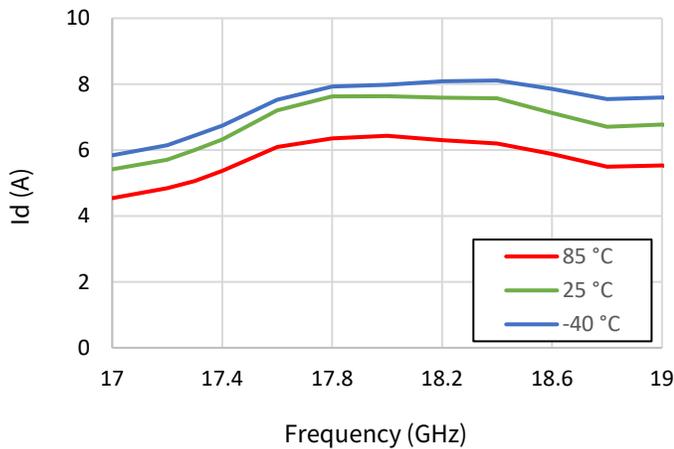
**Figure 3: Pout v. Frequency v. Temperature**



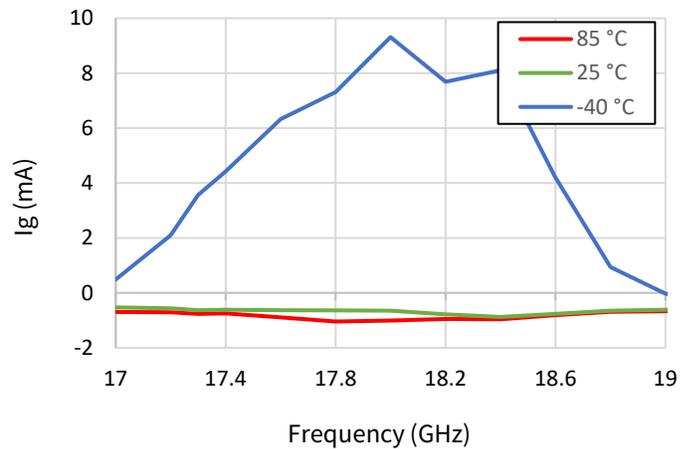
**Figure 4: PAE v. Frequency v. Temperature**



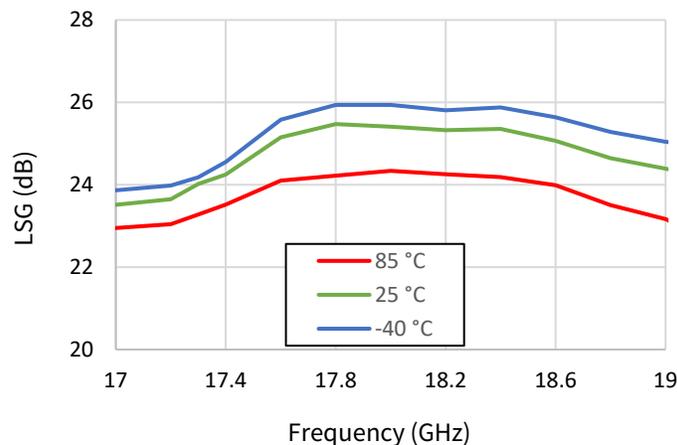
**Figure 5: Id v. Frequency v. Temperature**



**Figure 6: Ig v. Frequency v. Temperature**

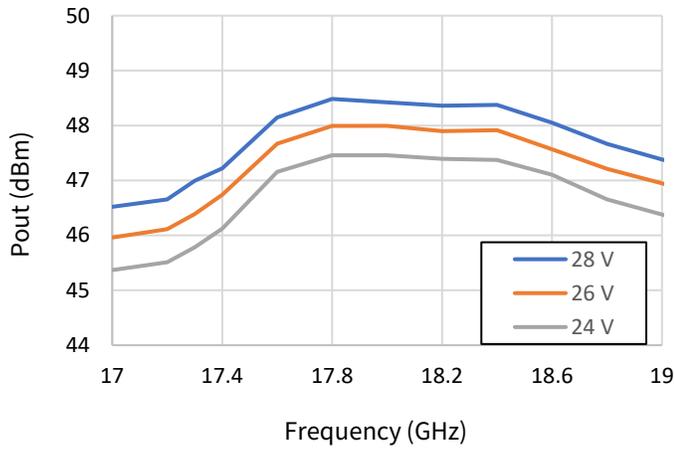


**Figure 7: LSG v. Frequency v. Temperature**

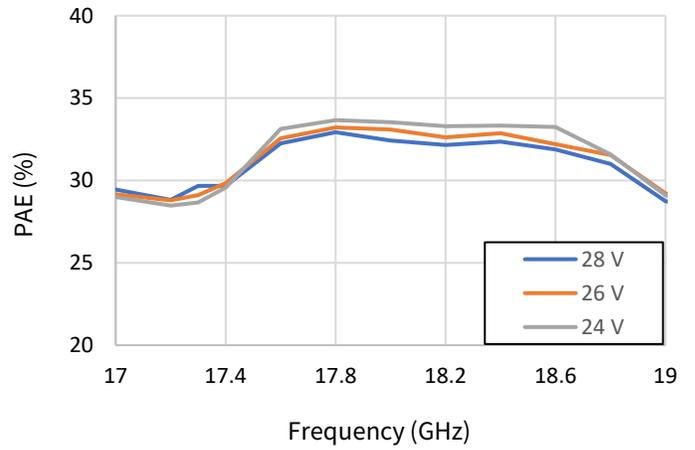


Test conditions unless otherwise noted: Vd=28 V, Idq=0.7A, CW, Pin = 23 dBm, T<sub>base</sub>=25 °C, Frequency: 17.8GHz

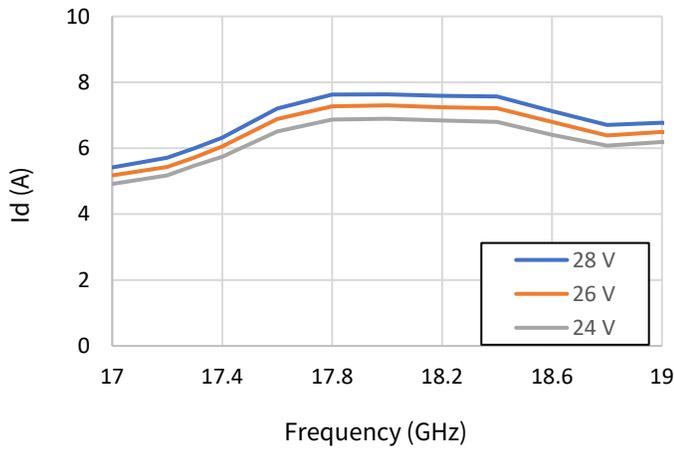
**Figure 8: Pout v. Frequency v. Vd**



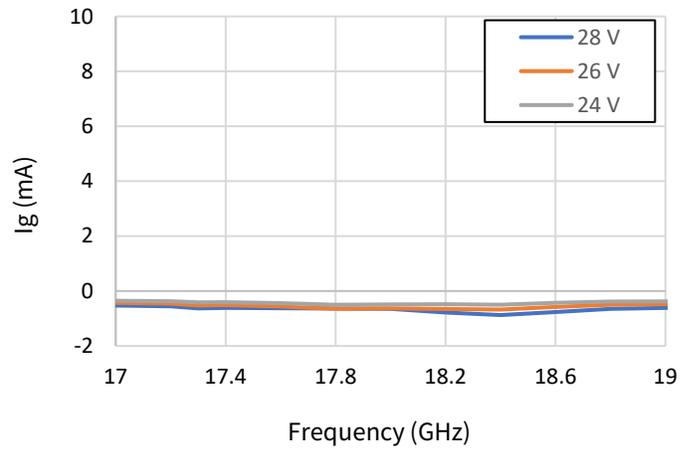
**Figure 9: PAE v. Frequency v. Vd**



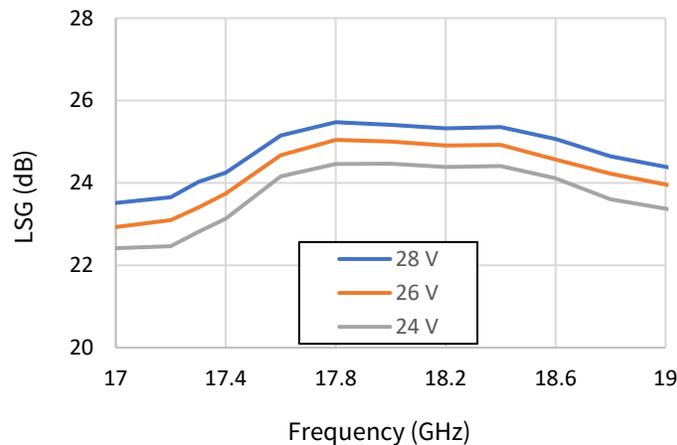
**Figure 10: Id v. Frequency v. Vd**



**Figure 11: Ig v. Frequency v. Vd**

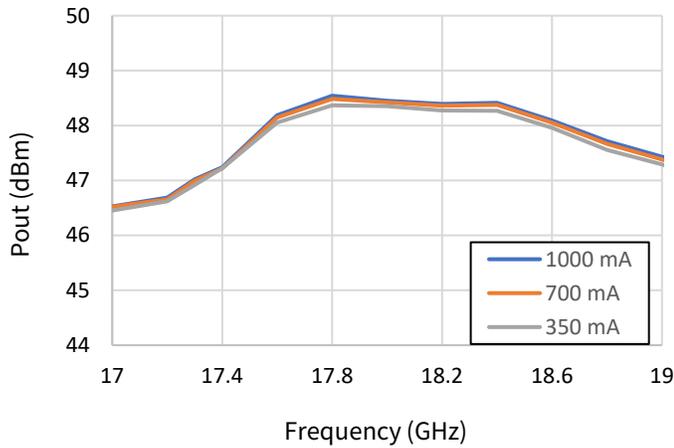


**Figure 12: LSG v. Frequency v. Vd**

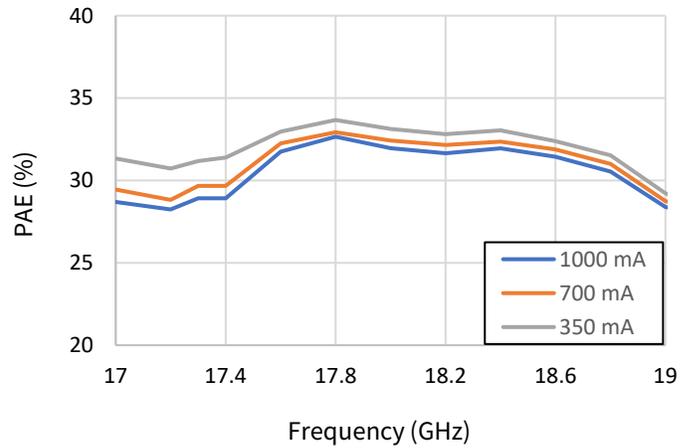


Test conditions unless otherwise noted:  $V_d=28\text{ V}$ ,  $I_{dQ}=0.7\text{ A}$ , CW,  $P_{in} = 23\text{ dBm}$ ,  $T_{base}=25\text{ }^\circ\text{C}$ , Frequency: 17.8GHz

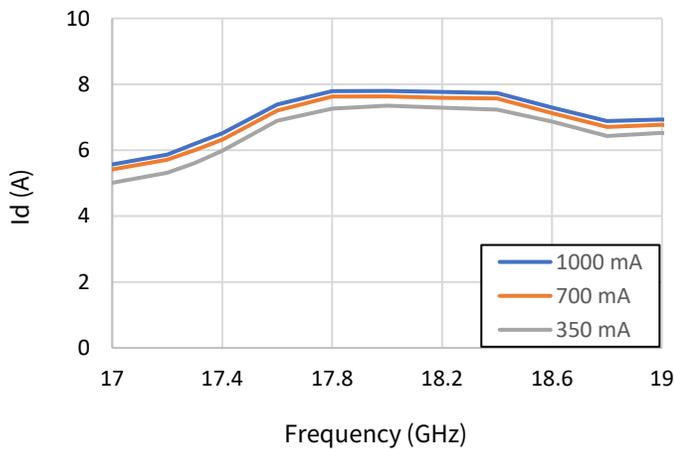
**Figure 13: Pout v. Frequency v. Idq**



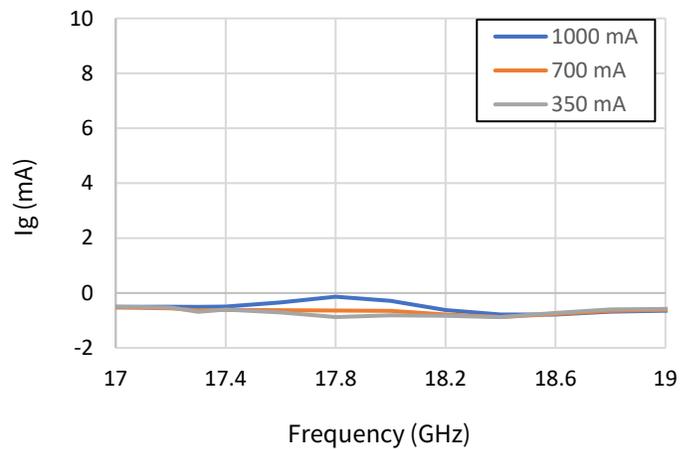
**Figure 14: PAE v. Frequency v. Idq**



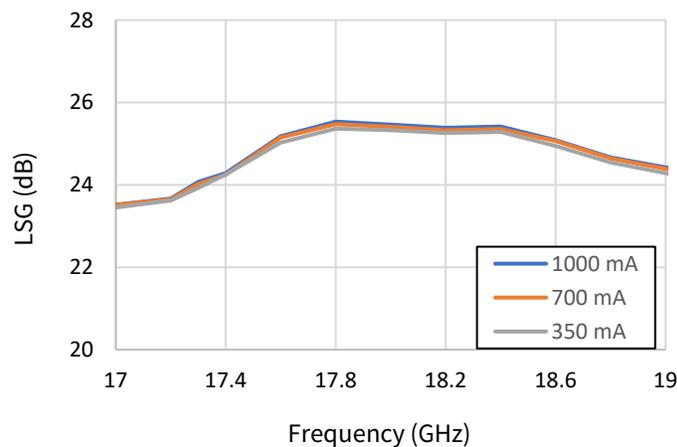
**Figure 15: Id v. Frequency v. Idq**



**Figure 16: Ig v. Frequency v. Idq**

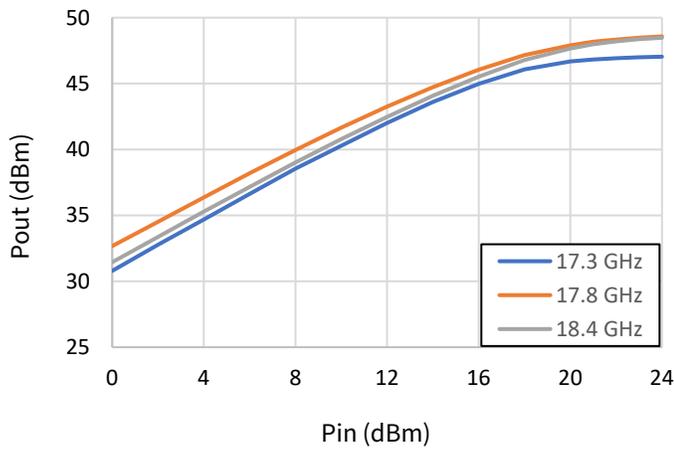


**Figure 17: LSG v. Frequency v. Idq**

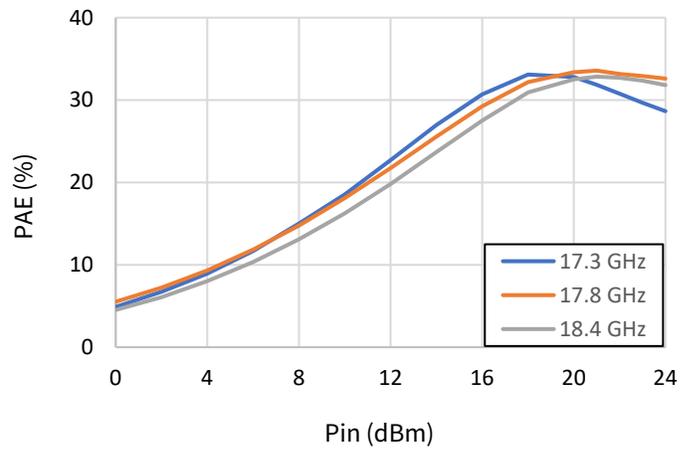


Test conditions unless otherwise noted:  $V_d=28\text{ V}$ ,  $I_{dq}=0.7\text{ A}$ , CW,  $P_{in} = 23\text{ dBm}$ ,  $T_{base}=25\text{ }^\circ\text{C}$ , Frequency: 17.8GHz

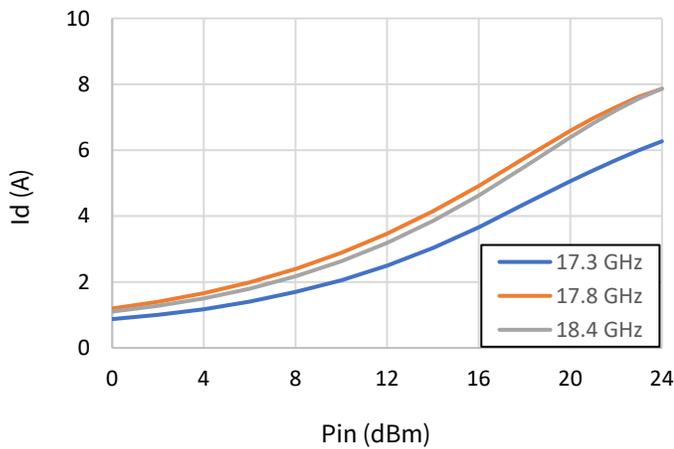
**Figure 18: Pout v. Pin v. Frequency**



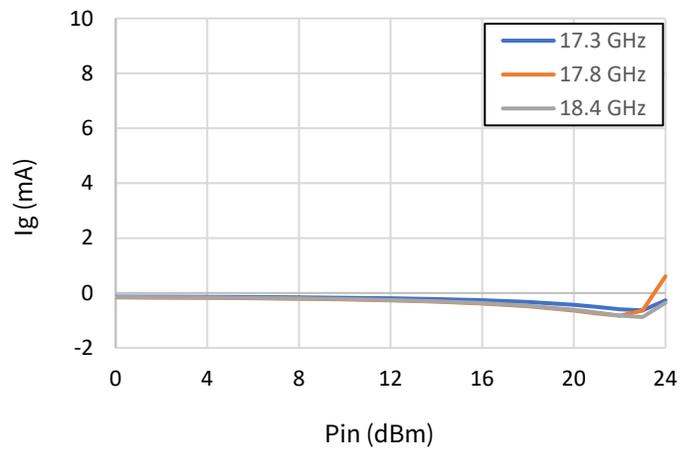
**Figure 19: PAE v. Pin v. Frequency**



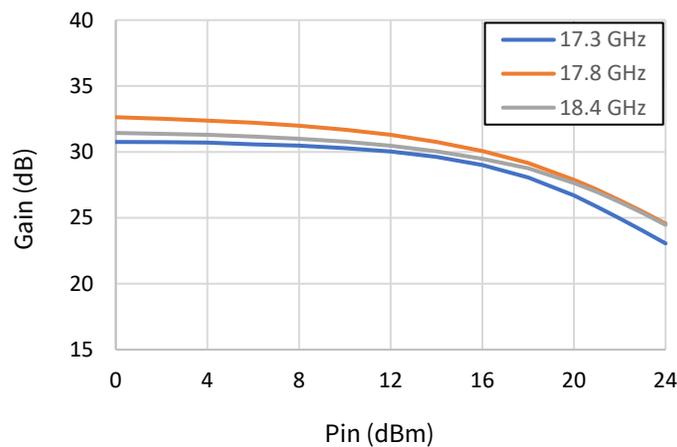
**Figure 20: Id v. Pin v. Frequency**



**Figure 21: Ig v. Pin v. Frequency**

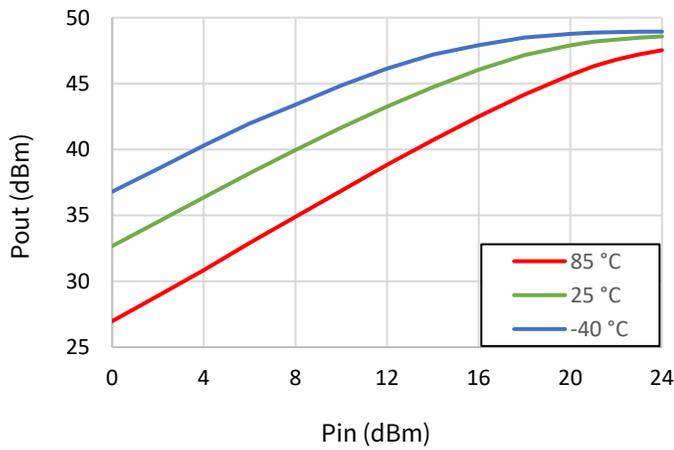


**Figure 22: Gain v. Pin v. Frequency**

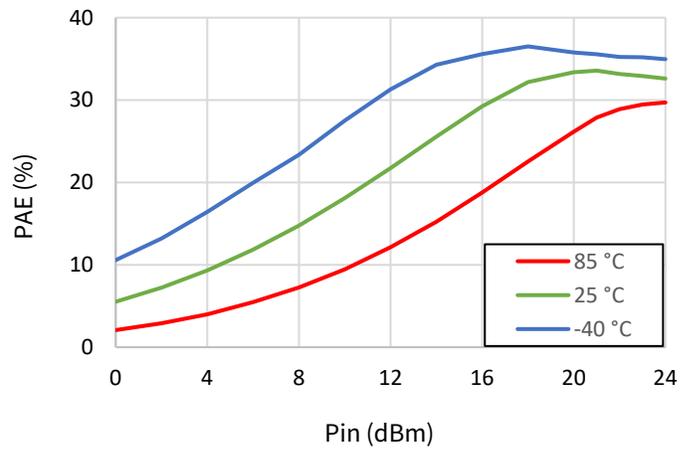


Test conditions unless otherwise noted:  $V_d=28\text{ V}$ ,  $I_{dq}=0.7\text{ A}$ , CW,  $P_{in} = 23\text{ dBm}$ ,  $T_{base}=25\text{ }^\circ\text{C}$ , Frequency: 17.8GHz

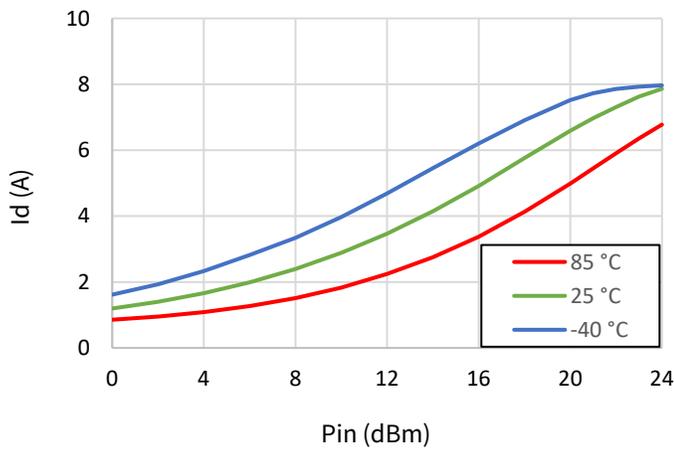
**Figure 23: Pout v. Pin v. Temperature**



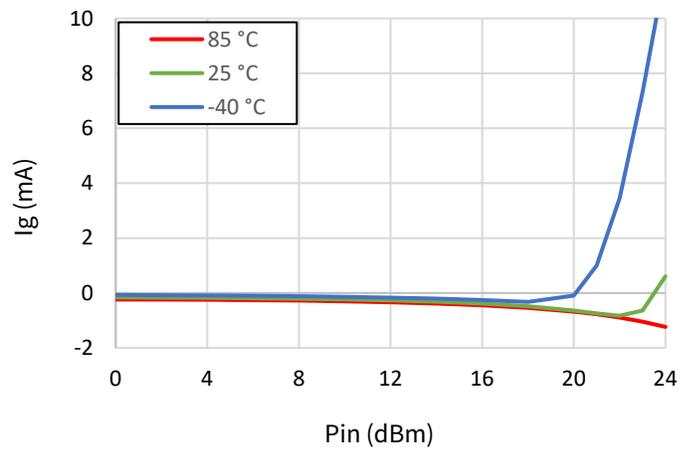
**Figure 24: PAE v. Pin v. Temperature**



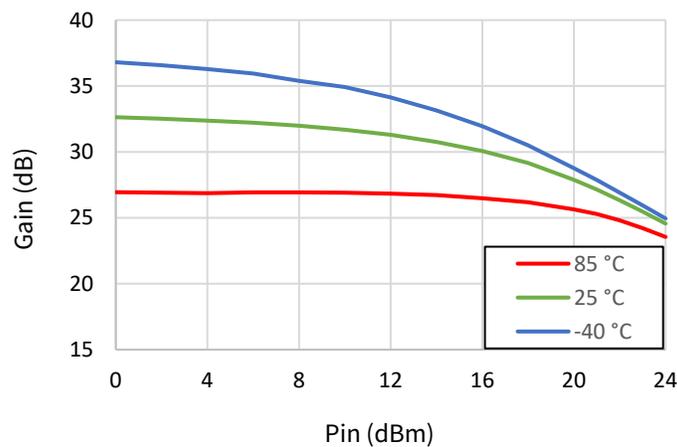
**Figure 25: Id v. Pin v. Temperature**



**Figure 26: Ig v. Pin v. Temperature**

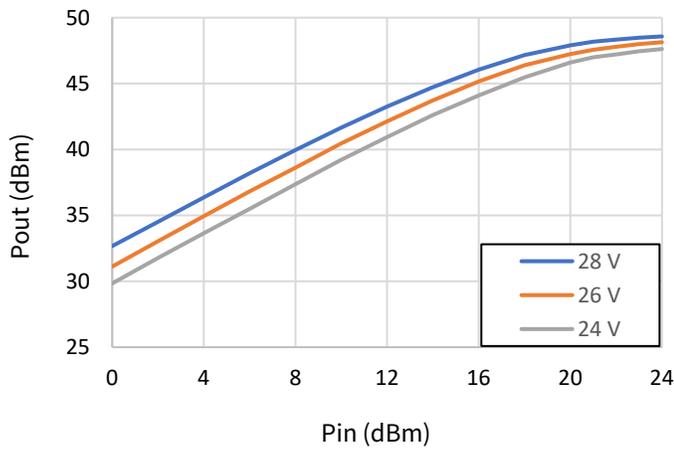


**Figure 27: Gain v. Pin v. Temperature**

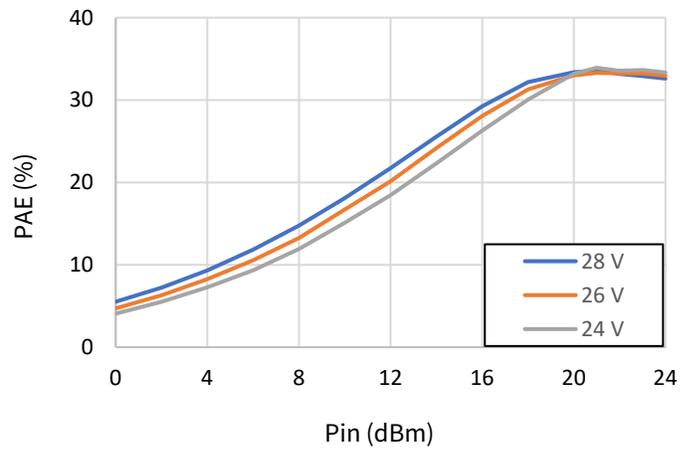


Test conditions unless otherwise noted: Vd=28 V, Idq=0.7A, CW, Pin = 23 dBm, T<sub>base</sub>=25 °C, Frequency: 17.8GHz

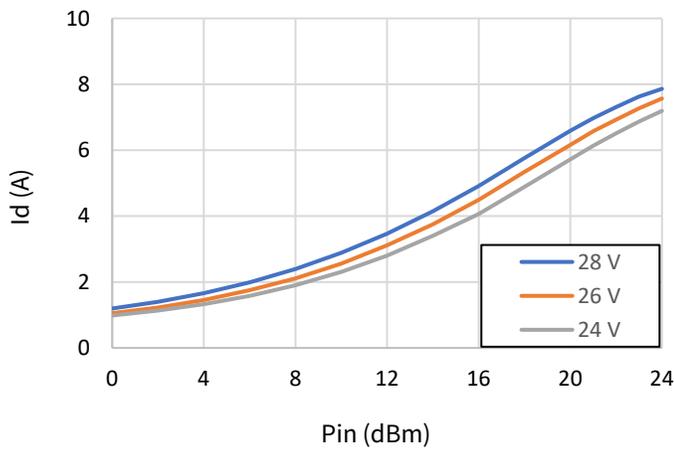
**Figure 28: Pout v. Pin v. Vd**



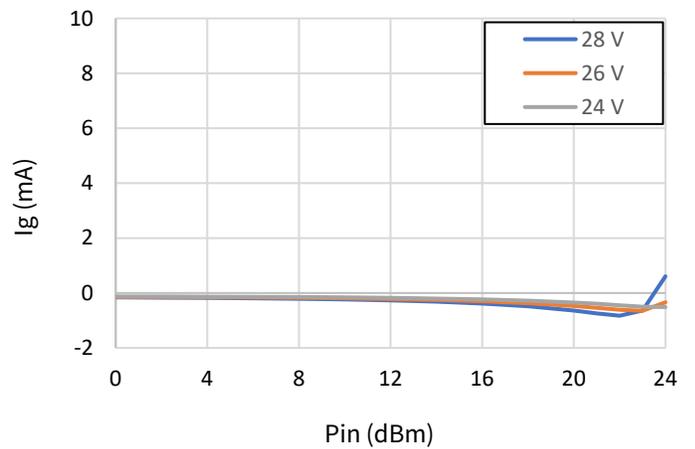
**Figure 29: PAE v. Pin v. Vd**



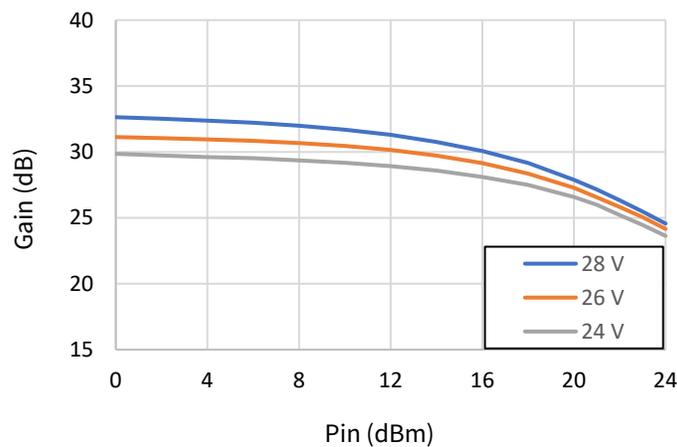
**Figure 30: Id v. Pin v. Vd**



**Figure 31: Ig v. Pin v. Vd**

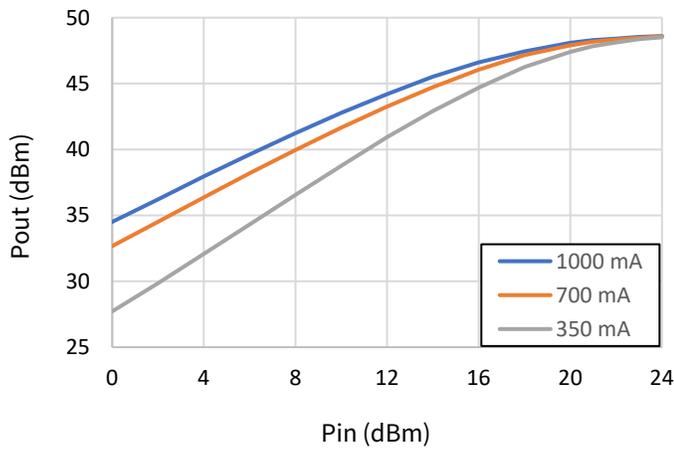


**Figure 32: Gain v. Pin v. Vd**

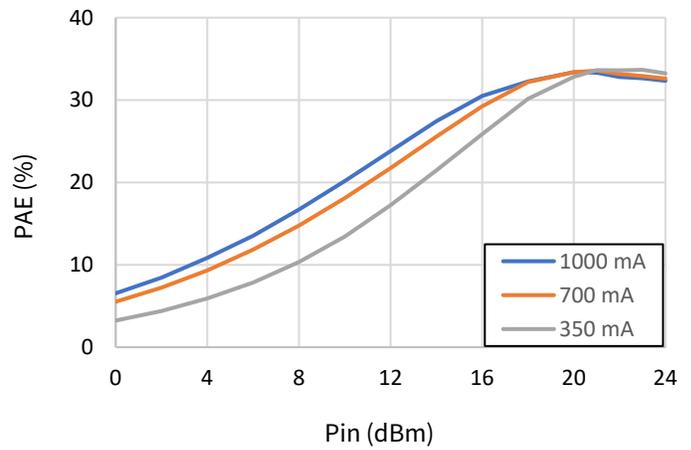


Test conditions unless otherwise noted:  $V_d=28\text{ V}$ ,  $I_{dq}=0.7\text{ A}$ , CW,  $P_{in} = 23\text{ dBm}$ ,  $T_{base}=25\text{ }^\circ\text{C}$ , Frequency: 17.8GHz

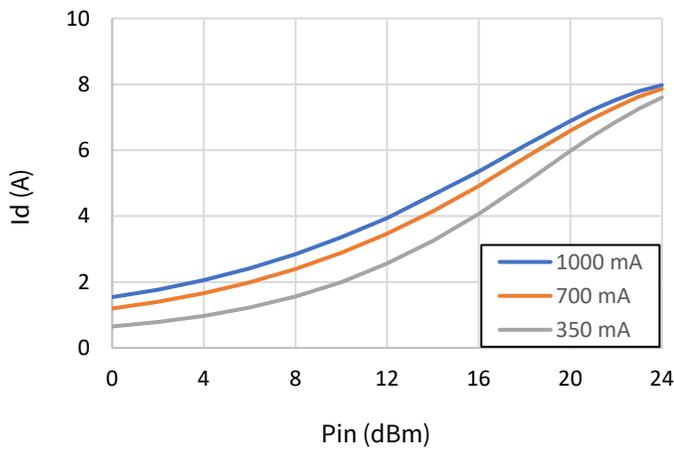
**Figure 33: Pout v. Pin v. Idq**



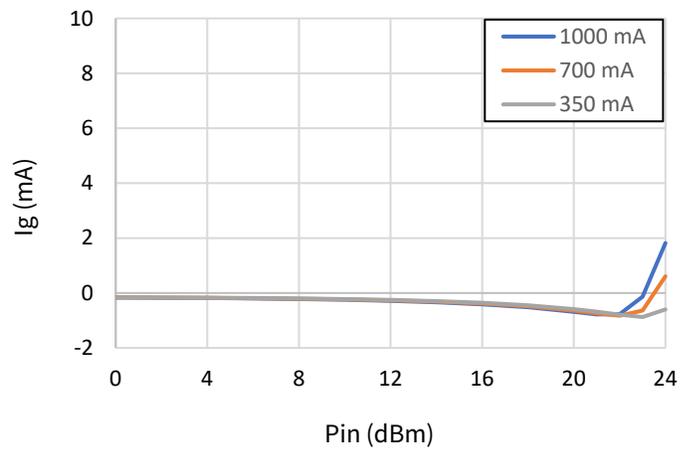
**Figure 34: PAE v. Pin v. Idq**



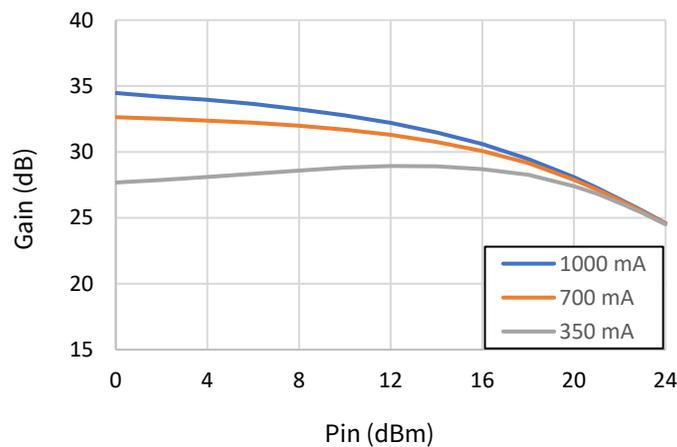
**Figure 35: Id v. Pin v. Idq**



**Figure 36: Ig v. Pin v. Idq**

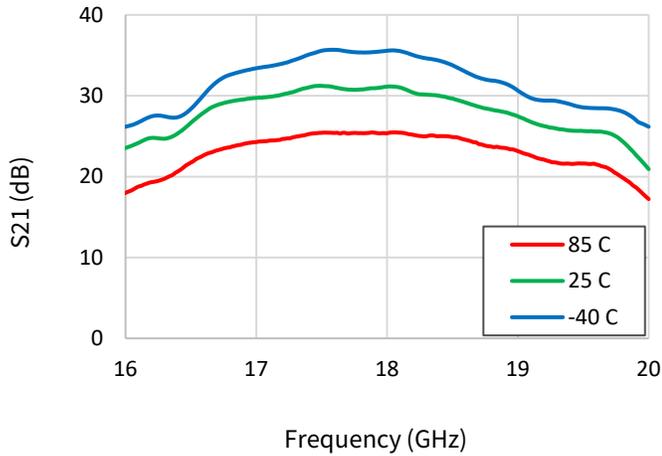


**Figure 37: Gain v. Pin v. Idq**

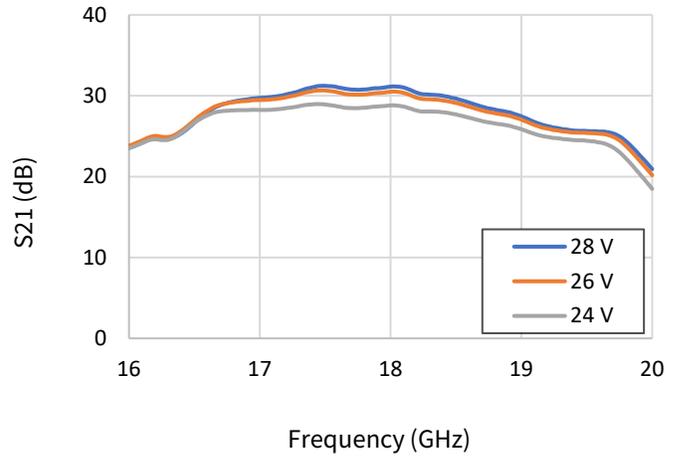


Test conditions unless otherwise noted: Vd=28 V, Idq=0.7A, CW, Pin = -20 dBm, T<sub>base</sub>=25 °C

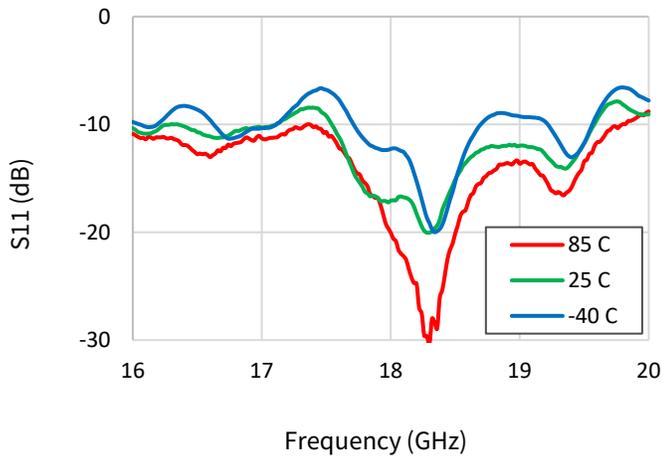
**Figure 38: S21 v. Frequency v. Temperature**



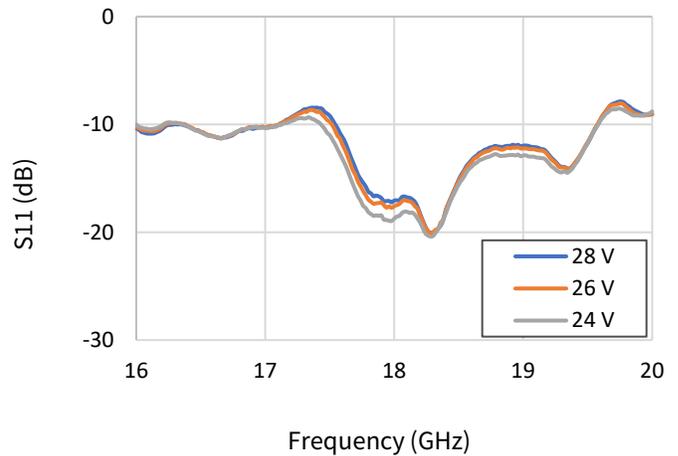
**Figure 39: S21 v. Frequency v. Vd**



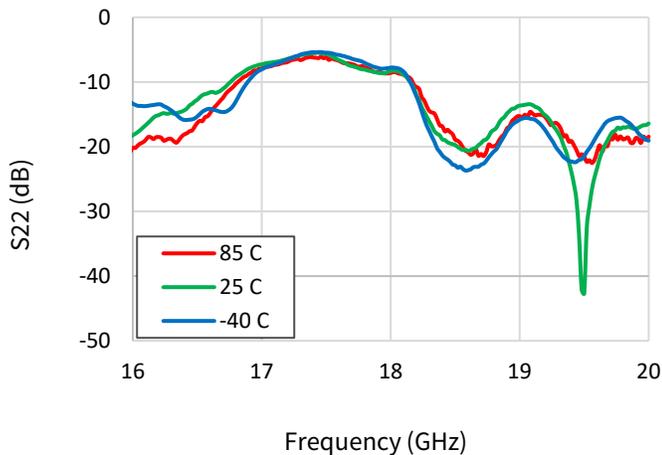
**Figure 40: S11 v. Frequency v. Temperature**



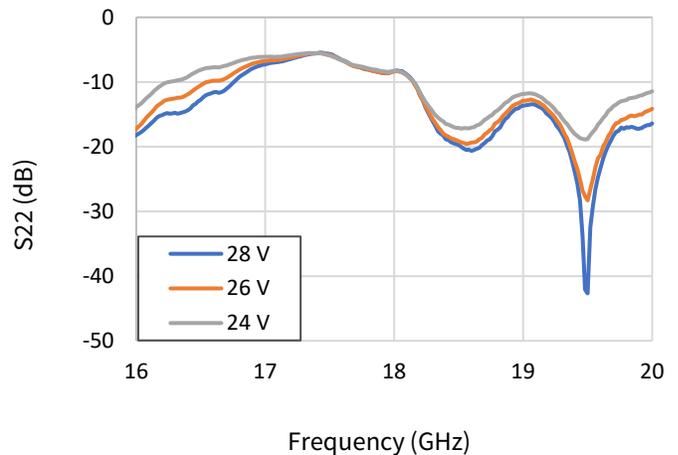
**Figure 41: S11 v. Frequency v. Vd**



**Figure 42: S22 v. Frequency v. Temperature**

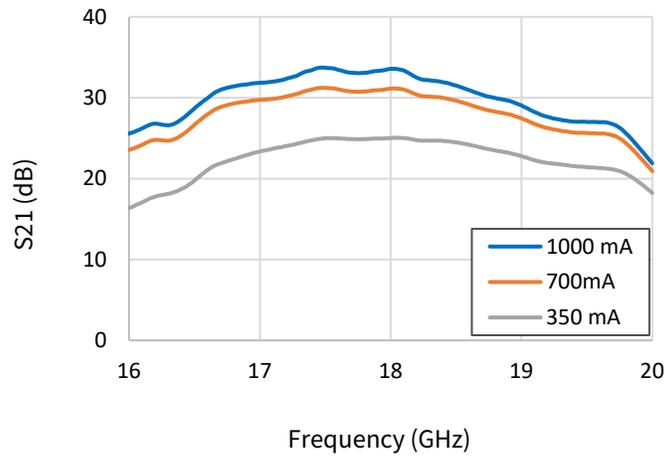


**Figure 43: S22 v. Frequency v. Vd**

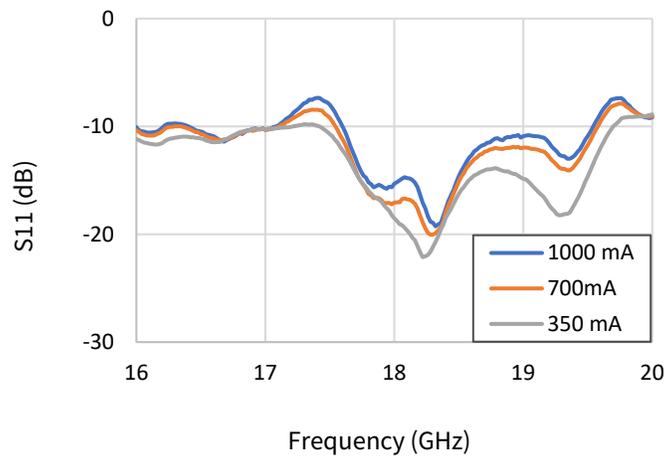


Test conditions unless otherwise noted:  $V_d=28\text{ V}$ ,  $I_{dq}=0.7\text{ A}$ , CW,  $P_{in} = -20\text{ dBm}$ ,  $T_{base}=25\text{ }^\circ\text{C}$

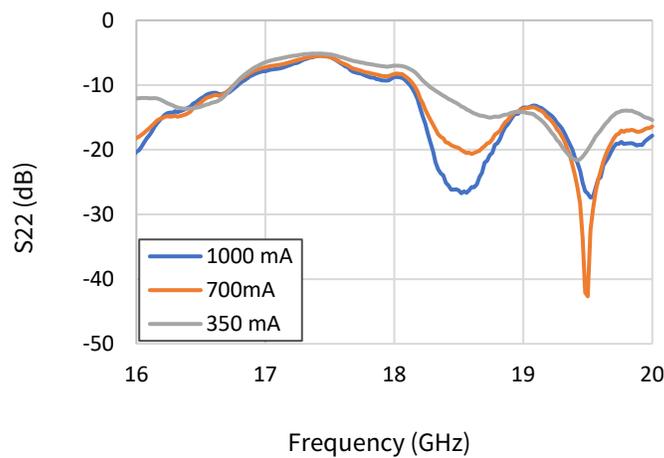
**Figure 44: S21 v. Frequency v. Idq**



**Figure 45: S11 v. Frequency v. Idq**

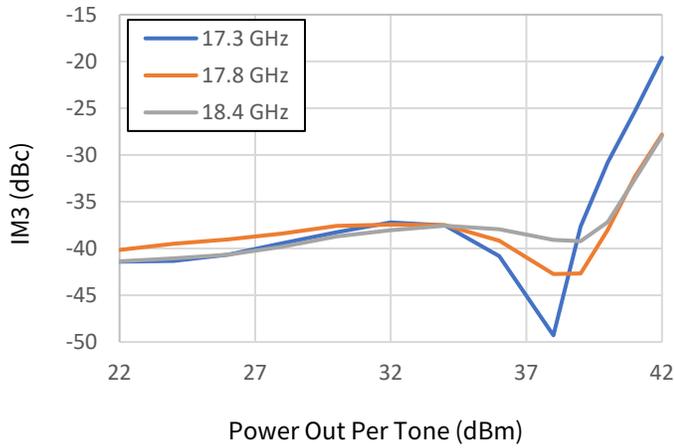


**Figure 46: S22 v. Frequency v. Idq**

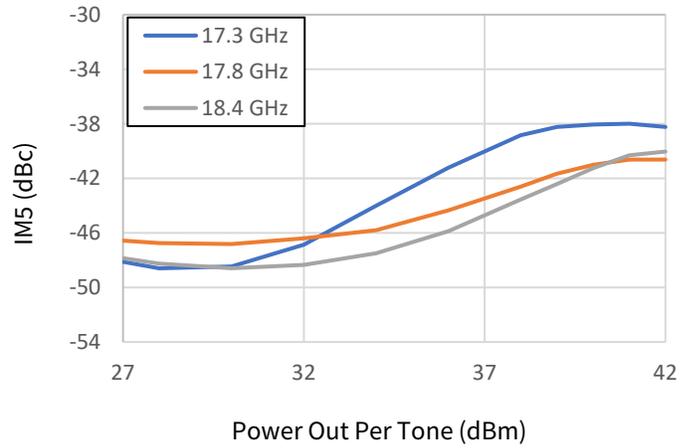


Test conditions unless otherwise noted:  $V_d=28\text{ V}$ ,  $I_{dq}=0.7\text{ A}$ , CW,  $P_{out}/\text{tone} = 41\text{ dBm}$ , Frequency = 17.8 GHz, Tone Spacing = 1 MHz,  $T_{base}=25^\circ\text{C}$

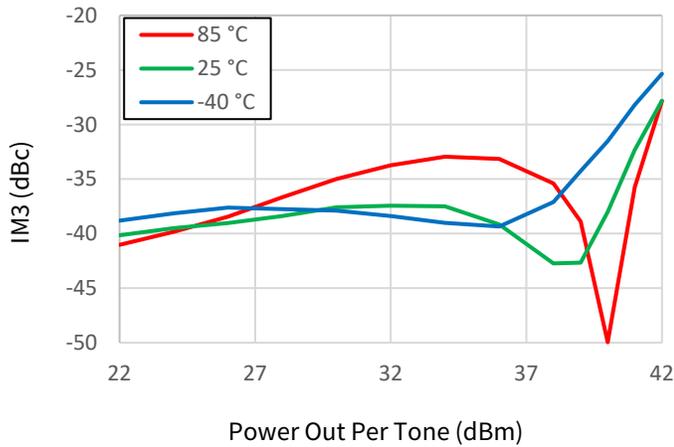
**Figure 47: IM3 v. Pout/tone v. Frequency**



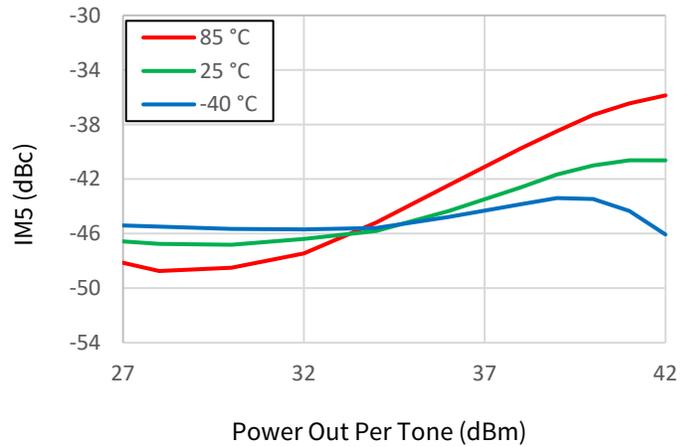
**Figure 48: IM5 v. Pout/tone v. Frequency**



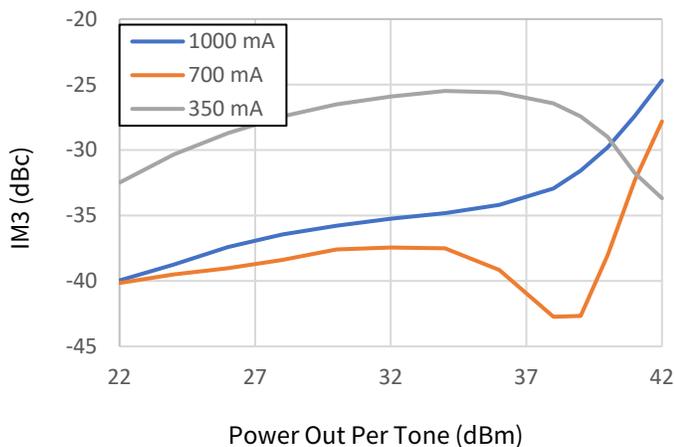
**Figure 49: IM3 v. Pout/tone v. Temperature**



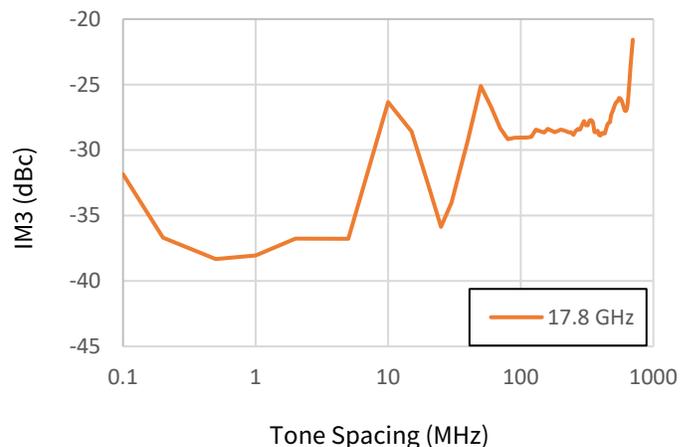
**Figure 50: IM5 v. Pout/tone v. Temperature**



**Figure 51: IM3 v. Pout/tone v. Idq**



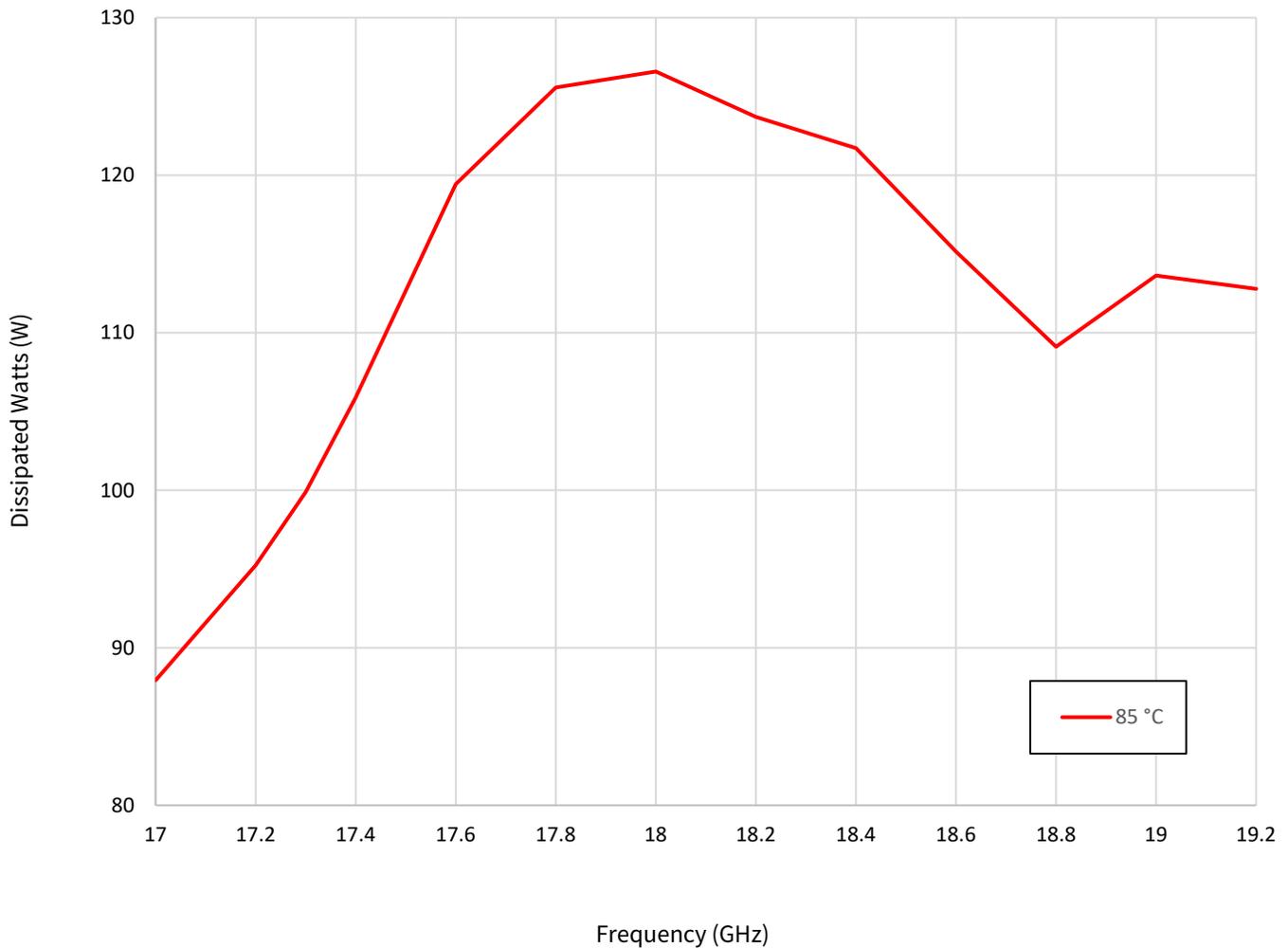
**Figure 52: IM3 v. Tone Spacing v. Frequency**



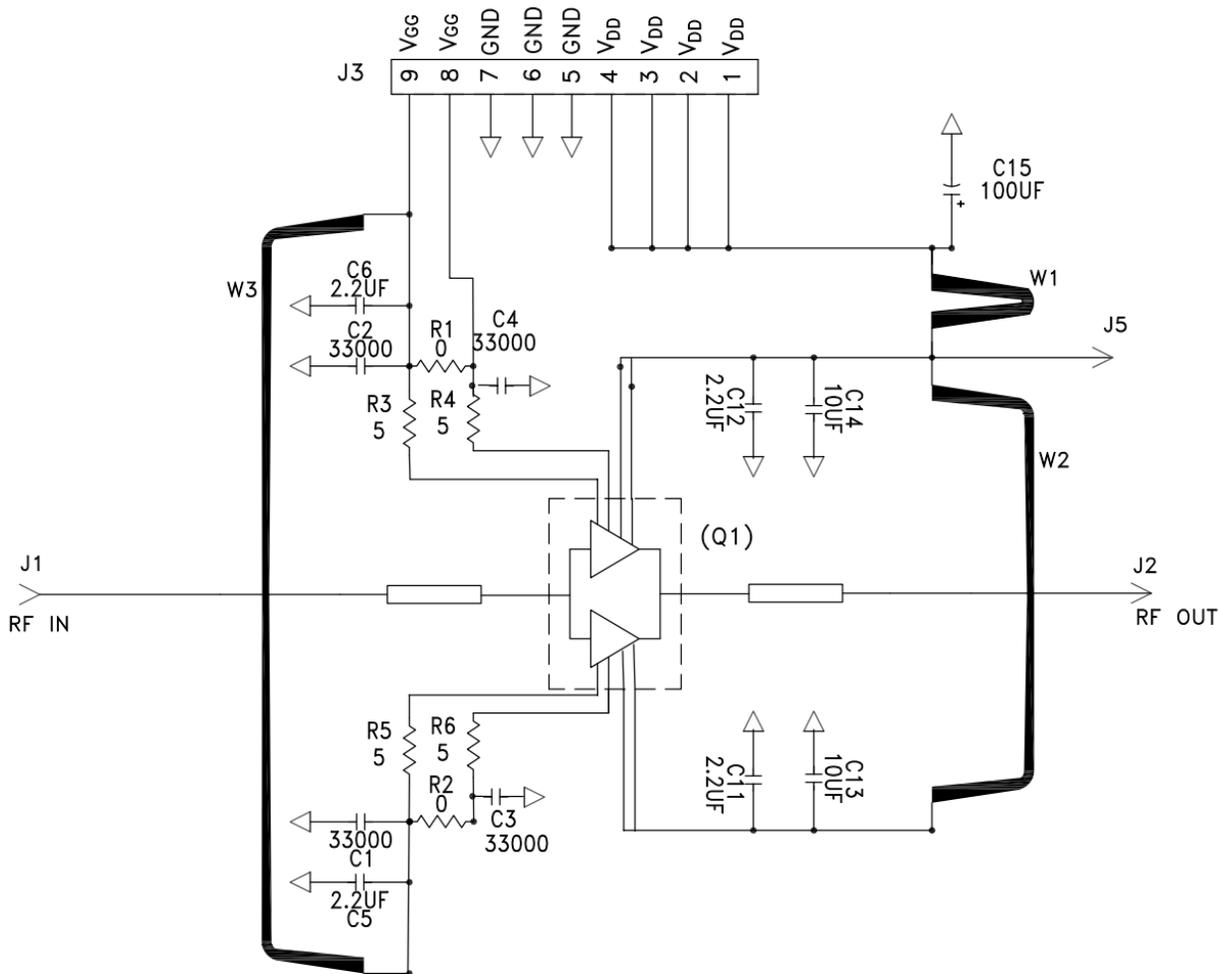
**Thermal Characteristics**

Parameter	Symbol	Value	Operating Conditions
Operating Junction Temperature	$T_J$	215.3	Freq = 17.8 GHz, $V_d = 28$ V, $I_{dq} = 700$ mA, $I_{drive} = 6.35$ A, $P_{in} = 23$ dBm, $P_{out} = 47.2$ dBm, $P_{diss} = 125.3$ W, $T_{case} = 85^\circ\text{C}$ , CW
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.04	

**Power Dissipation v. Frequency ( $T_{case} = 85^\circ\text{C}$ )**



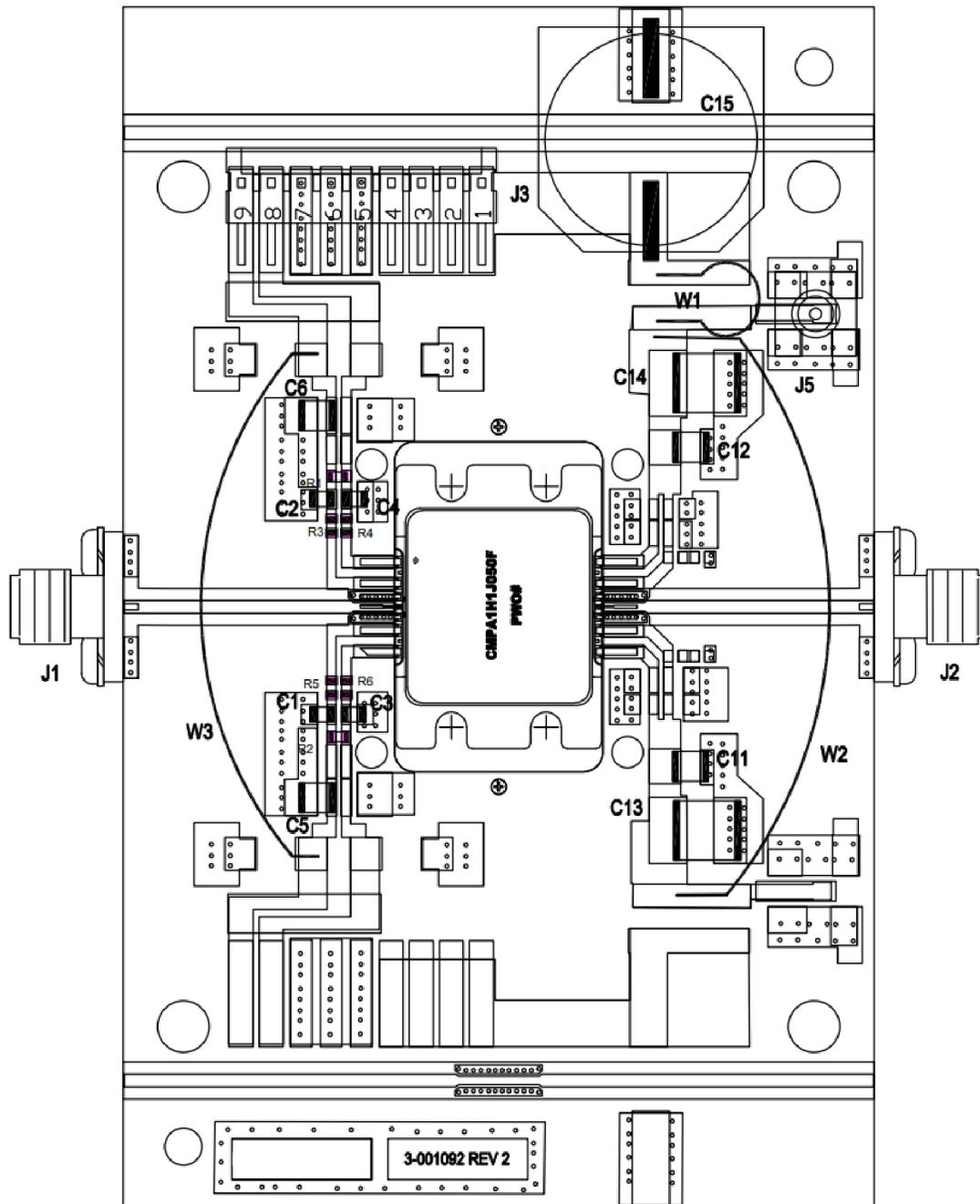
**CMPA1H1J050F-AMP Evaluation Board Schematic Drawing**



**CMPA1H1J050F-AMP Evaluation Board Bill of Materials**

Reference Designator	Description	Qty
C1,C3,C2,C4	CAP, 33000PF, 0805,100V, X7R	4
C5,C6,C11,C12	CAP, 2.2UF, 100V, 10%, X7R, 1210	4
C13,C14	CAP, 10UF, 100V, 10%, X7R, 2220	2
C15	CAP, 100 UF, 20%, 160V, ELEC	1
W1, W2, W3	WIRE, 18 AWG ~ 1.75"	3
J1,J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST, 20MIL	2
J3	HEADER RT>PLZ .1CEN LK 9POS	1
J5	CONN, SMB, STRAIGHT JACK RECEPTACLE, SMT, 50 OHM, Au PLATED	1
Q1	CMPA1H1J050F, MMIC	1
-	PCB, ROGERS 6035 HTC, 2.5x4.0x0.020 IN	1
-	BASEPLATE, CU, 2.5 X 4.0 X 0.5 IN	1
-	2-56 SOC HD SCREW 1/4 SS	4
-	#2 SPLIT LOCKWASHER SS	4
R1,R2	RES,1/16W,0603,1%,0 OHMS	2
R3,R4,R5,R6	RES,1/16W,0603,1%,5.1 OHMS	4

**CMPA1H1J050F-AMP Evaluation Board Assembly Drawing**



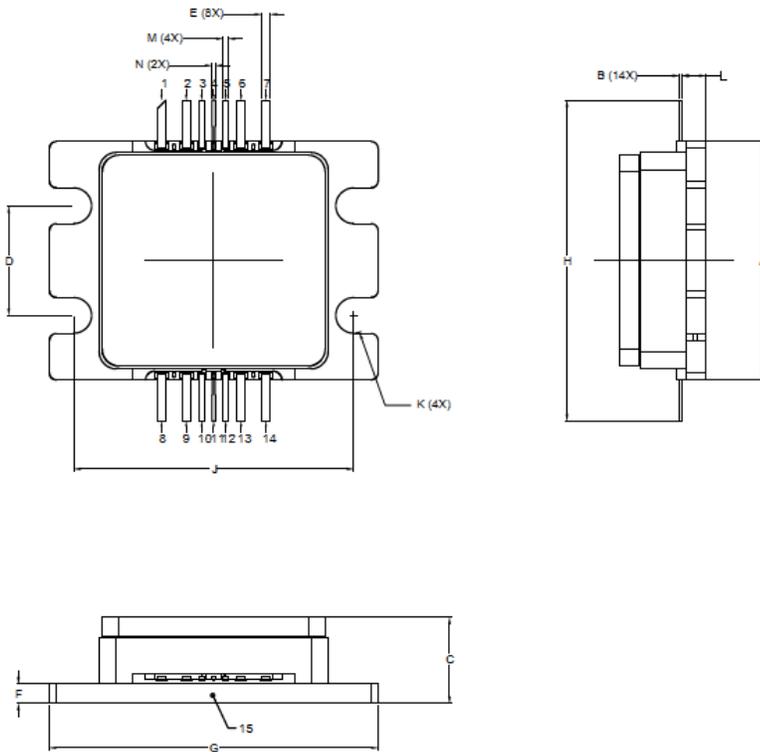
**Bias On Sequence**

1. Ensure RF is turned-off
2. Apply pinch-off voltage of -5 V to the gate ( $V_g$ )
3. Apply nominal drain voltage ( $V_d$ )
4. Adjust  $V_g$  to obtain desired quiescent drain current ( $I_{dq}$ )
5. Apply RF

**Bias Off Sequence**

1. Turn RF off
2. Apply pinch-off to the gate ( $V_g=-5V$ )
3. Turn off drain voltage ( $V_d$ )
4. Turn off gate voltage ( $V_g$ )

**Product Dimensions**



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
5. ALL PLATED SURFACES ARE N/1AU

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.679	0.691	17.25	17.55
B	0.003	0.006	0.076	0.152
C	0.234	0.261	5.94	6.63
D	0.307	0.323	7.80	8.20
E	0.016	0.032	0.406	0.813
F	0.047	0.063	1.194	1.600
G	0.936	0.954	23.77	24.23
H	0.912	0.930	23.16	23.62
J	0.795	0.811	20.19	20.60
K	∅0.094	∅0.110	∅2.39	∅2.79
L	0.062	0.078	1.575	1.981
M	0.006	0.022	0.152	0.559
N	0.004	0.018	0.102	0.457

PIN	DESC.	PIN	DESC.
1	Bias MMIC2, Gate St3	8	Bias Drain MMIC 2
2	Bias MMIC2, Gate St1&ST2	9	Bias Drain MMIC 2
3	GND	10	GND
4	RF IN	11	RF OUT
5	GND	12	GND
6	Bias MMIC1, Gate St1&ST2	13	Bias Drain MMIC 1
7	Bias MMIC1, Gate St3	14	Bias Drain MMIC 1

## Electrostatic Discharge (ESD) Classification

Parameter	Symbol	Class	Classification Level	Test Methodology
Human body Model	HBM	TBD	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D
Charge Device Model	CDM	TBD	ANSI/ESDA/JEDEC JS-002 Table 3	JEDEC JESD22 C101-C

## Product Ordering Information

Part Number	Description	MOQ Increment	Image
CMPA1H1J050F	17.3 – 18.4 GHz, 60W GaN MMIC		
CMPA1H1J050F-AMP	Evaluation Board w/ PA	1 Each	

## Notes & Disclaimer

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